Revision History

Schematics taken from P151-A00-X24 MS-8889 00A

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1)Page 10,13,18 of the original design (P151) has been delete.
 2)Page 10,12 U816,U817,U818,U811(single gate) share one ACT08/S08.
 3. Page 13 a. P300 change reference to P600.
          b.Add P300 (long D-sub)for SEC D-sub.
 4.Page 14 a.Remove P602.
     b.Add S_OUT1,S_IN1,AV_OUT1,AV_IN1,J1,J2 connector.
 5.Page 16,17 Modify power supply solution.
   a.PWM from SC1102A,SC1541-3.3V,SC1565 share one ISL6529.
   b.FBVDDQ is transfered from Q800,U4 by 5V.
   c.SC2610 change to HIP6012.
 002-0624
 1)Page 16 a.Remove C1250,C1251,R1076,R1071,Q10,U4,Q800.
           b.FBVDDQ Remove Q800 and U4 ,Add U812/NIKO-1085S/TO-263.
           c.0905 and 0201 from 45N02LD change to 55N02LD for low Rdson.
 2)page 17 Remove Q9,R2086,Q8,R2087.
 3)page 11 Add R2217/33ohm and C2495 for "DVOCLK_IN".
 4) page 15 change Text Note "PCT DEVID =253" to "PCT DEVID =283".
 5)page 17 a.R2085 change value to 4.7K.
          b.U3 change refernce to U813.
 1)Page 16 ADD C1250,C1251,R1076,C1071.
2)page 9 a.ADD RP16/47ohm for "DVOBD12" and "DVOBD13".
b.Add solder side heat sink "K201"
 3)page 11 Add SAA7104/5.
00A-0626
 1)Page 9 - Change the 47ohm RPack to 33ohm RPack.
2)Page 2 - a.ADD C106/4.7U for "12V to qnd".
           b.R80,R81,R82,and R83 from 5% change to 1%.
 3)Page 16 - U812 from L1085/3A change to L1084/5A for FBVDDQ.
 4)Page 14 - S OUT1 & S IN1 chage to P500 & P501.
 1)Page 2 - a.ADD thermal sensor RT1 (in GPU solder side).
           b.ADD C113/220PF "AGPVREECG" pull down.
 2)Page 14 - Remove J1.
 4)Page 16 - a.Remove C1406.
           b.ADD CE1,CE2,CE3,CE4 for EMI (FBVDD bypass).
            c.ADD R617/1K,R618/6.8K,C1406/470PF for U814.
 5)Page 17 - ADD C2307,C2308 for "FBVDDQ"
 00A-0702
1)Page 2 - a.Make R80 = 49.9 ohms 1%, Make R81 =
              NO_STUFF, Make R82 = 56.2 ohms 1%, and
              Make R83 = NO_STUFF.
            b.C110 from 0.1uF change to 0.01uF
              C113 from 220PF change to 0.22uF
 2)Page 16/17 - R617, R618, R624, R616, R1080, R1082,
                R1210, R1104, R2085, R2083, R2082 all be 1%.
1)Page 2 - Add R111,R112 Oohm for thermal sensor.
2)Page 11 - Remove U1 7104H/QFP64.
 1)Page 11 - Remove R2218.
 2)Add 8.a H/W MONITOR for channel only, Medion NO_STUFF.
 3)Page 17 - Add C2235 for 12V to GND.
 00A-0708
 1)Page 2 - RT1 footprint from SMD change to DIP.
 00A-0709
 1)Page 16 - Remove C1276,C1264,C1366,C1267,C1301,C1379,C1304.
 2)Page 5,6,7,8 - Add C550-C565 / 10PF / 0402 from
                  "FB(A/B/C/D)CLK(0/0-/1/1-) total 16pcs for
                  EMI engineer.
 00A-0712
 1)Need to change Power net on R2088 sheet 17 to "12V".
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Need to change Power Net on D658 sheet 17 to "12V".

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00A-0716
1)Page 2 - a.R80 and R81 needs to be tied to "GND". right now it is tied to VDDQ.
           b.R82 and R83 needs to be tied to "VDDQ".
             Pin 'R82.2' moved to net 'VDDQ'.
             Din 'R83 2' moved to net 'VDDO'
             Pin 'R81.1' moved to net 'GND'.
2)Page 2 - Pin 'Q901.3' moved to net 'AGP_MDT2'. This is the collector.
           Pin 'Q901.1' moved to net 'AGP_MDT4'. This is the BASE.
           Pin 'Q901.2' moved to net '3.3V'. This is the Emitter.
3)Page 2 - Component value changes:
            a.R98 please change from 5.76K to 6.49K 1%.
            b.R110 and R105 change from 1.5K to 2.32K 1%.
            c.Q613 - Changed from 2N7002 to IRLML2502 (N-ch 20V 3A 0.08 on resistence).
           d.Q901A - change to MMBT4403LT1.
00B-0728
1)Page 2 - C108 pin 1 & Q901A pin "E" and R94 pin 1 from 3.3V change to 3.3VL. 2)Page 16 - C1303 from SMD change to DIP for low ESR.
3)Page 17 - a.Add CE4-CE8 for EMI 3.3V to FBVDDQ.
           b.D658 pin2 connector to "CP_CAP",D658 pin 3 connector to C2273 pin 1.
00B-0730
1) Dage 2 = Add H200/FDC6301N P93/0P P101/121K P108/121K P96/1K for ACDVrefor
2)Page 16 - R1076 change to 6.49 ohm / 1%.
             C1250 change to 68nF.
             R1210 change to 13K / 1%.
            C1448 change to 47nF.
             C1252 change to 2.2nF.
3)Page 17 - R1067 change to 10 ohm / 1%.
             C2230 change to 100nF.
             R2081 change to 10K / 1%.
            C2234 change to 2.7nF.
             R2075 change to 1.58K / 1%.
             R2084 change to 49.9K / 1%.
1)We need to change the Device ID from 0x283 to 0x281.
 So that means R959 is a NO STUFF and R258 is 10K.
2)Page 17 - R1121 change to 3.16K / 1%.
1)Page 17 - C2234 change to 2.7nF.
2)Page 15 - Add JP2 connector to "DVOD21 and GND.
3)Page 13 - P300 pin 17,18 floating.
UNB-UBUZ
1)Page 16 - Add Cap C1264,C2309,C2310(dual layout) for layout.
2)Page 18 - Add R58,R59,R60 and UZ for FAN power.
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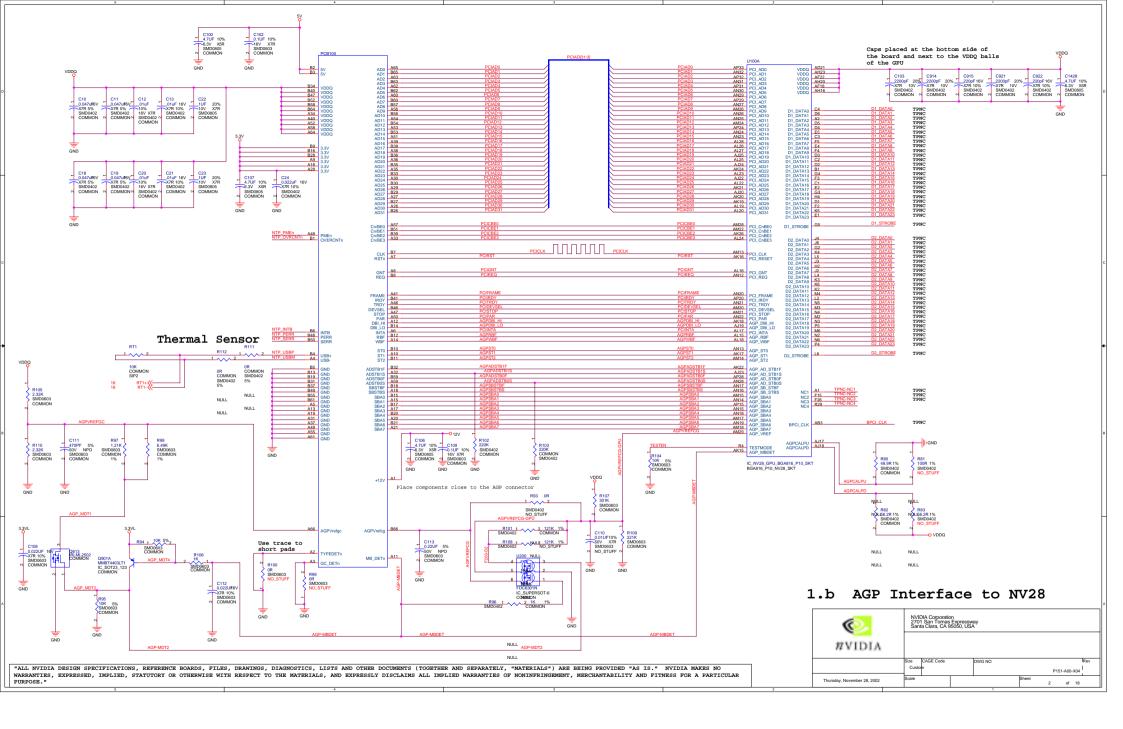
Sub Assemblies	Description	
COMMON	Components are stuffed for all SKUs	
NO_STUFF	Components are not stuffed	
PRI DVI I	Components stuffed for Primary VGA	
PRI PROT	Components stuffed for Primary Protection	
SEC DVI I	Components stuffed for Secondary DVI	
SEC PROT	Components stuffed for Secondary Protection	
AGP3VFBDQ	Components stuffed for AGP 3.3V to FBVDD	
FBVDD-FBDQ	Components stuffed for FBVDDQ 2.5V to FBVDD	D
PLL-SEQ	Components stuffed for PLL Sequence	
PWR-SEQ	Components stuffed for Power Sequence	
PWR-SEQ-BP	Components stuffed for Power Sequence By-PASS	
NVVDD-2602	Components stuffed for NVVDD Power	
FB 2610 SWT	Components stuffed for FBVDD Power	
SC1541	Components stuffed for 3.3VL Fixed	
SC1565	Components stuffed for SC1565 - 3.3VL Adj.	
FB64LO	Components stuffed for FBA DATA and FBD DATA	
FB64UP	Components stuffed for FBC DATA and FBD DATA	r
SER-PROM	Components stuffed for Serial PROM	
PAR-PROM	Components stuffed for Parallel PROM	
FAN HS-LFT	Components stuffed for Fan / Blower	
_	left of the GPU	
FAN_SNK	Fan Sink Component	
HEAT_SNK	Heat Sink Component	
VIVO	Components stuffed for Video IN/OUT	
	SAA7104 Video Out	С
VIDO-7104		
CX-ENC-TVOUT	Components stuffed for CX25871 - TV-OUT	
SOCKET	Components stuffed for Socket	
64MB-4MX16 BRACKET	Components stuffed for Mem-CFG: 64MB (4Mx16) memory IO Bracket / VGA-DIN-DVI-I	
BRACKET-VGA	IO Bracket / VGADVI-I	
FB 2610 LDO	Components stuffed for FBVDDQ Power	
FBVDD_ADJ	Components to adjust FBVVD out voltage.	
FBVDQ_ADJ	Components to adjust FBVVDQ out voltage.	٠
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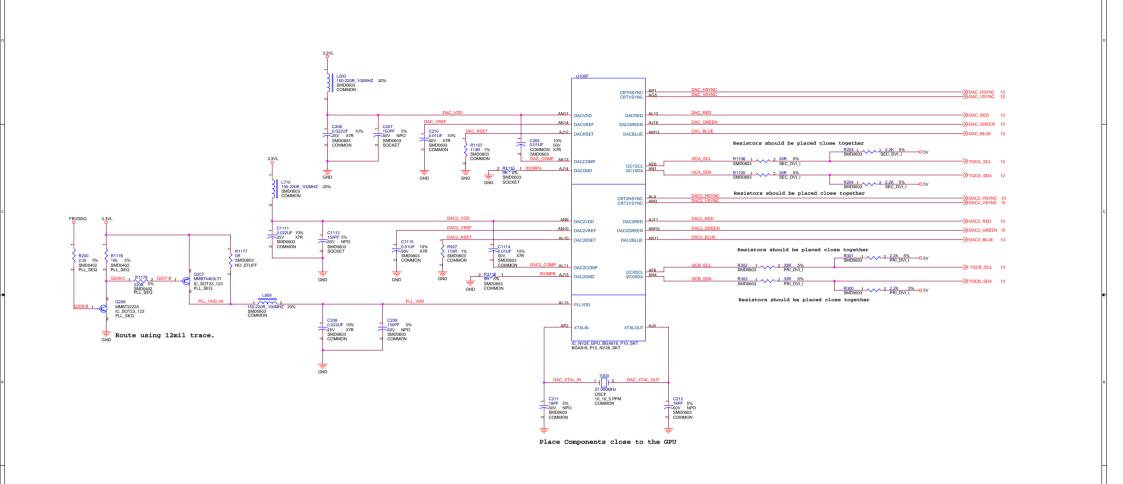
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3.g DVI__ / VGA Connectors / HotPlug
3.h S-Video Connector / Filter / Bracket
4.a NV STRAP // P/S-ROM
5.a Power Sequence / 3.3VL Supp
5.b NVVDD Power Supply
5.c.FBVDDQ Power Supply
5.c.FBVDDQ Power Supply

Legend:

TPNC = Test Point - Not Connected







1.c NV28 .. PLL / DAC / I2C

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NVIDIA		NV28PL / DAC / I2C							
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